

**FIG. 1**

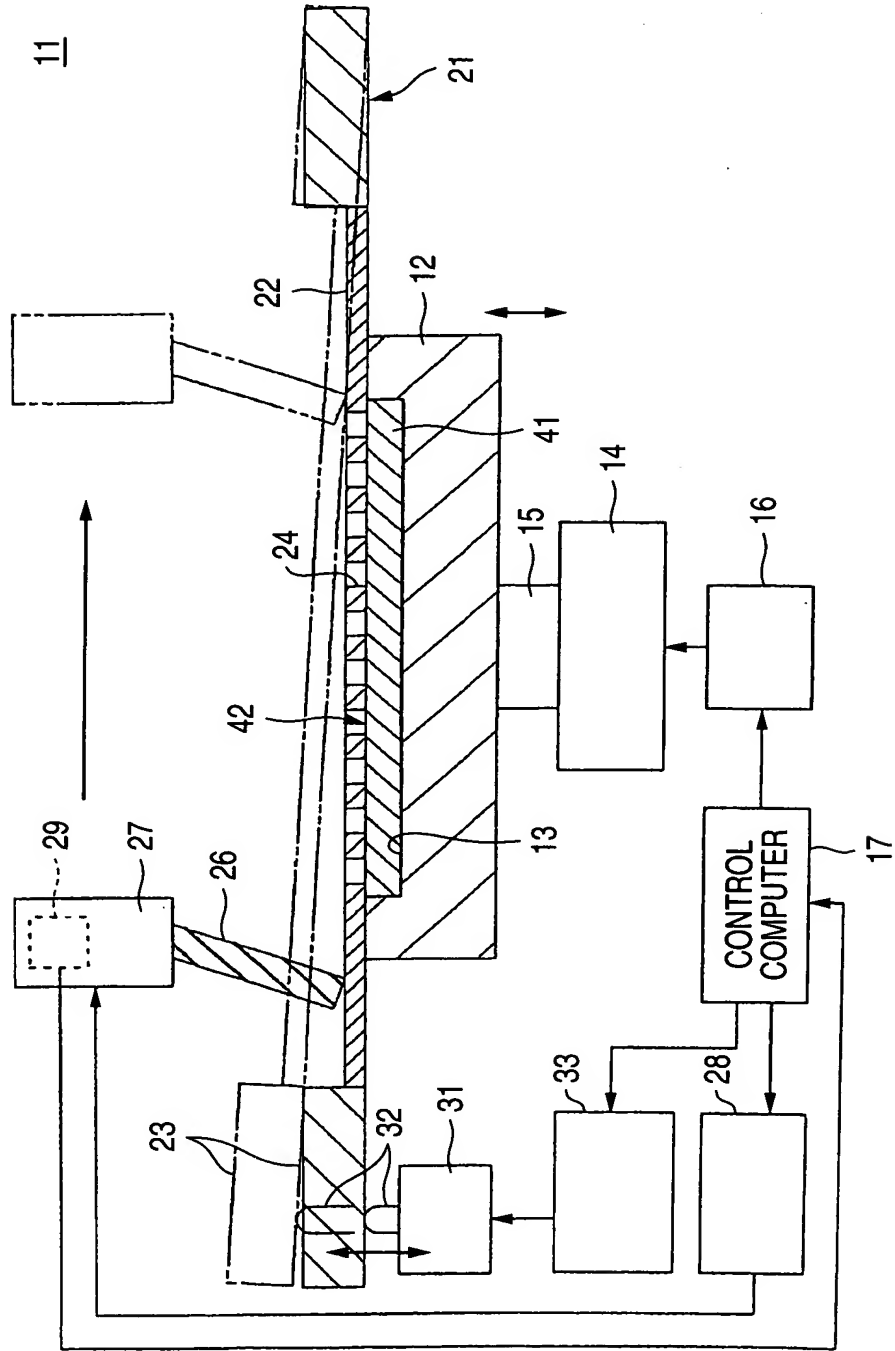


FIG. 2

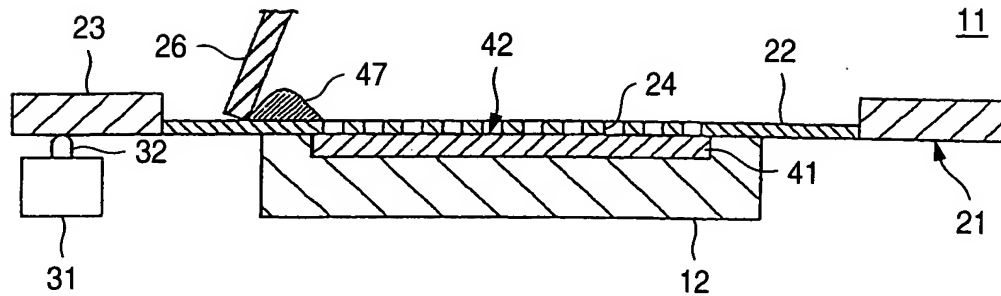


FIG. 3

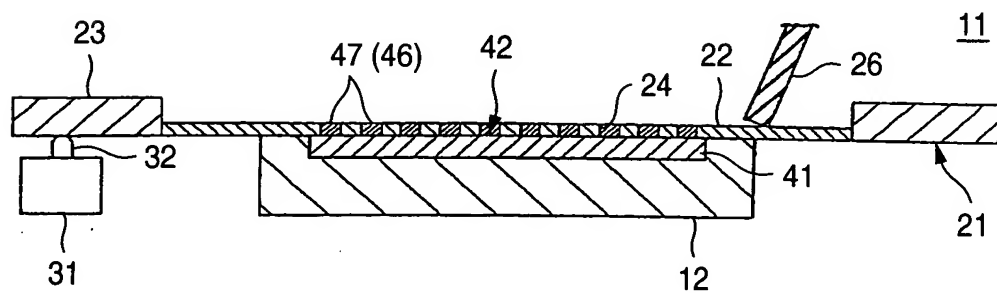
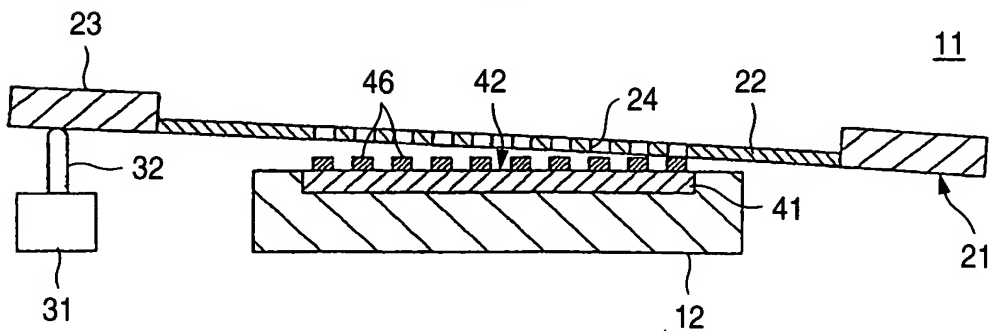


FIG. 4



A cross-sectional diagram of a multi-layered cylindrical assembly. The central core consists of alternating layers of material 22 (diagonal hatching) and material 24 (white). This core is surrounded by a layer of material 45 (wavy pattern), which is further enclosed by a layer of material 44 (cross-hatching). The outermost layer is material 41 (diagonal hatching). A thin layer of material 43 (horizontal hatching) is positioned between the inner layers and the outer shell. Labels 42 and 46 point to specific features at the ends of the assembly.

This cross-sectional view shows a semiconductor device with two active regions. Each active region consists of a substrate layer 43, a thin layer 42, a layer 24, a layer 47 (46), and a top layer 45. The two active regions are separated by a central region 22. The device is bounded by side walls 21 and 44. The bottom surface is labeled 41.

FIG. 8

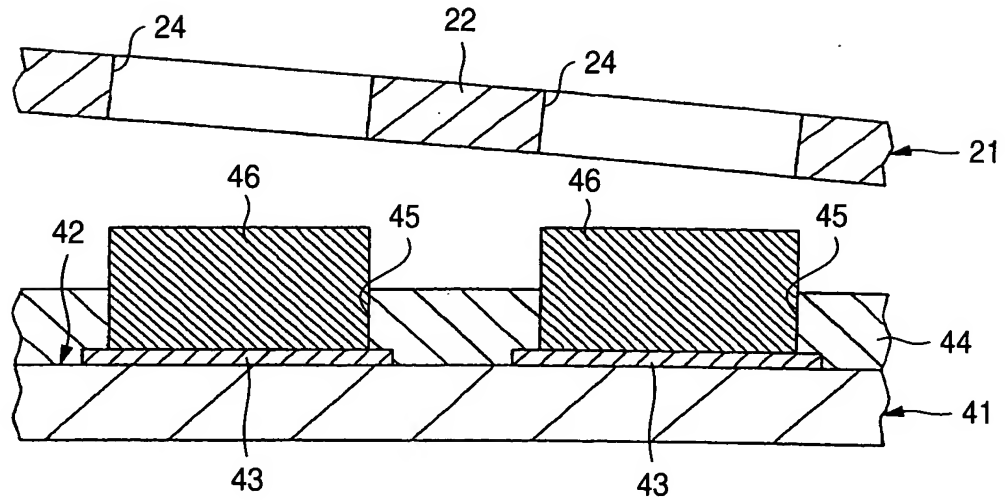


FIG. 9

